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22 March 1965

MEMORANDUM FOR THE RECORD

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SUBJECT: Trip Report --

15, 16, and 17 March 1965

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The trip was made to ascertain progress on the Chip Processor, under contract to and to discuss the Sepratron Processor, a new processing innovation proposed by and presented to the TDB on 3 March 1965.

The Chip Processor, due for delivery by 31 March 1965, is progressing satisfactorily. However, two requirements levied by the technical representative will probably delay delivery to 30 April 1965 or 15 May 1965. These requirements are: (a) increasing the size of the chip magazines from a 16 mount holder size to 36 mount holders, and (b) redesign of the method of initial immersion of the film chip into the developer solution. This was designed as slow input which would result in the processed chip being darker on the bottom due to that portion of the chip being in the developer for a longer time than the top of the chip. The contractor was asked to design a method of dropping the chip (in the chip mount) into the developer solution so that initial developing action is uniform over the entire chip. These actions will probably result in a request from the contractor for some additional funding as well as the time extension.

Of special interest is that is also designing the largest color processor (for original film) that has been built. Physically, this processor will be nearly 50 feet long by approximately 8 feet wide by 12 feet high. All transport will be by liquid-air bearings so that the film will not be touched from supply to take-up. Additionally, pumps, air and chemical mix will take-up nearly as much space as the processor itself. This effort, an extremely sensitive one, is being designed for SAC as the eventual recipient.

is the prime contractor on the overall effort, and is the probable contracting office.

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Development Branch, P&DS



